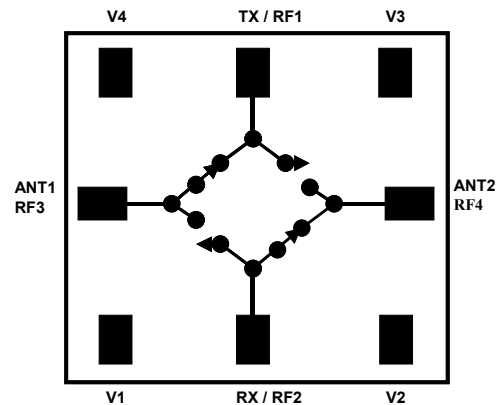


DC-6GHz DPDT Diversity Switch

Features:

- ◆ 3x3x0.9mm Packaged pHEMT Switch
- ◆ Very High Tx-Rx isolation
- ◆ Suitable for WLAN 802.11a and 802.11b/g Applications
- ◆ Filtronic Advanced GaAs pHEMT Technology
- ◆ Low Insertion Loss
- ◆ Excellent low control voltage performance

Functional Schematic



Description and Applications:

The FMS2007QFN is a low loss linear Double-Pole Double-Throw dual band diversity switch designed for use in WLAN applications. The die is fabricated using the Filtronic FL05 0.5 μ m switch process technology, which offers leading edge performance optimised for switch applications. Typical applications are for UNII, Hiperlan, 802.11a and 802.11b/g systems that employ two antennas for transmit and receive diversity.

Electrical Specifications: (T_{AMBIENT} = 25°C, V_{ctrl} = 0V/(2.4,3.3V), Z_{IN} = Z_{OUT} = 50 Ω)

| Parameter | Simulated Conditions | Min | Typ | Max | Units |
|--------------------|---------------------------------------|-----|------|-----|-------|
| Insertion Loss | 2.4GHz | | 0.9 | | dB |
| Insertion Loss | 6GHz | | 1.15 | | dB |
| Return Loss | 2.4GHz | | 18 | | dB |
| Return Loss | 6GHz | | 15 | | dB |
| Tx-Rx Isolation | 2.4GHz | | -37 | | dB |
| Tx-Rx Isolation | 6GHz | | -25 | | dB |
| 2nd Harmonic Level | 2.4, 6 GHz, Pin = 20dBm, Vctrl = 2.4V | | -70 | | dBc |
| 3rd Harmonic Level | 2.4, 6 GHz, Pin = 20dBm, Vctrl = 2.4V | | -70 | | dBc |
| Switching speed | Vctrl=2.4V, Pin=20dBm | | 30 | | nS |

Note: External DC blocking capacitors are required on all RF ports (typ: 47pF)

Absolute Maximum Ratings:

| Parameter | Symbol | Absolute Maximum |
|-----------------------|--------|------------------|
| Max Input Power | Pin | +36dBm |
| Control Voltage | Vctrl | +5V |
| Operating Temperature | Toper | -40°C to +100°C |
| Storage Temperature | Tstor | -55°C to +150°C |

Note: Exceeding any one of these absolute maximum ratings may cause permanent damage to the device.

Truth Table:

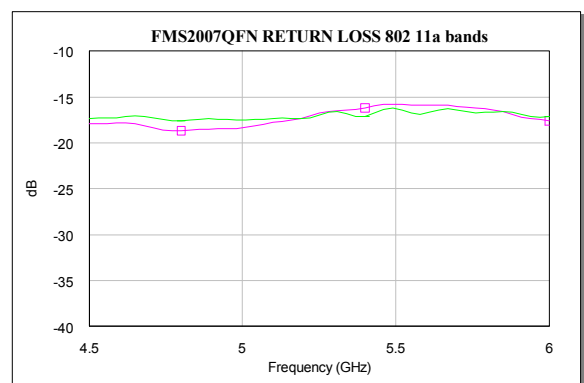
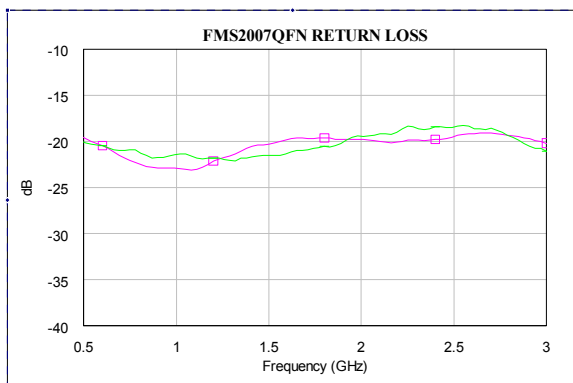
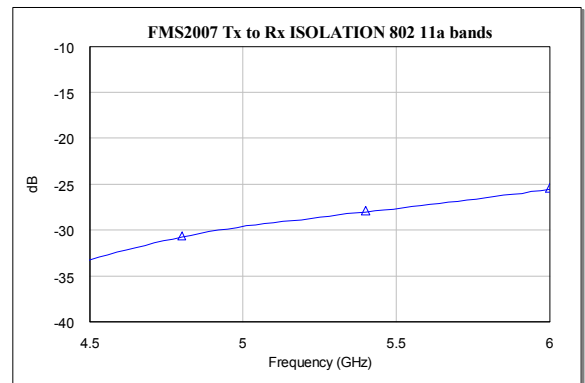
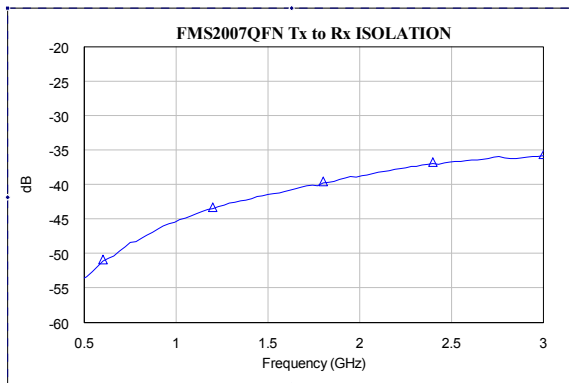
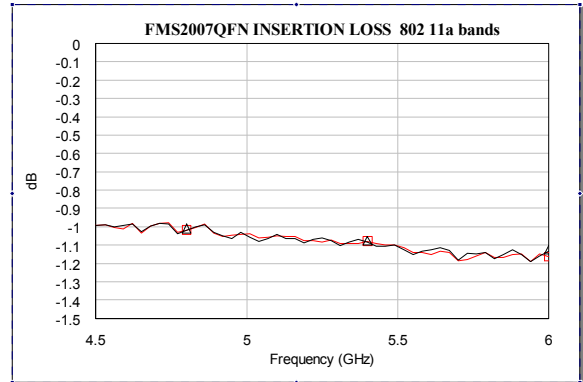
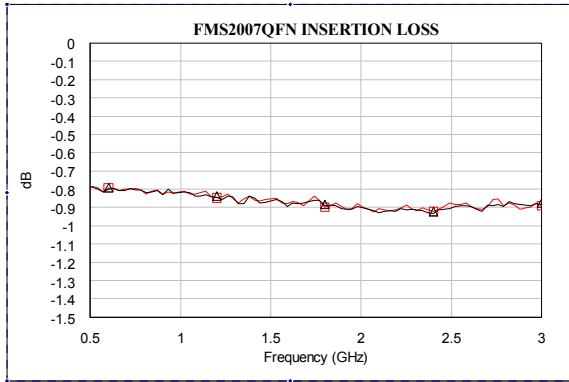
| Switch State | V1 | V2 | V3 | V4 | RX ANT1 | RX ANT2 | TX ANT2 | TX ANT1 |
|--------------|------|------|------|------|----------------|----------------|----------------|----------------|
| 1 | High | Low | Low | Low | Insertion Loss | Isolation | Isolation | Isolation |
| 2 | Low | High | Low | Low | Isolation | Insertion Loss | Isolation | Isolation |
| 3 | Low | Low | High | Low | Isolation | Isolation | Insertion Loss | Isolation |
| 4 | Low | Low | Low | High | Isolation | Isolation | Isolation | Insertion Loss |
| 5 | Low | High | Low | High | Isolation | Insertion Loss | Isolation | Insertion Loss |
| 6 | High | Low | High | Low | Insertion Loss | Isolation | Insertion Loss | Isolation |

General Test Conditions:

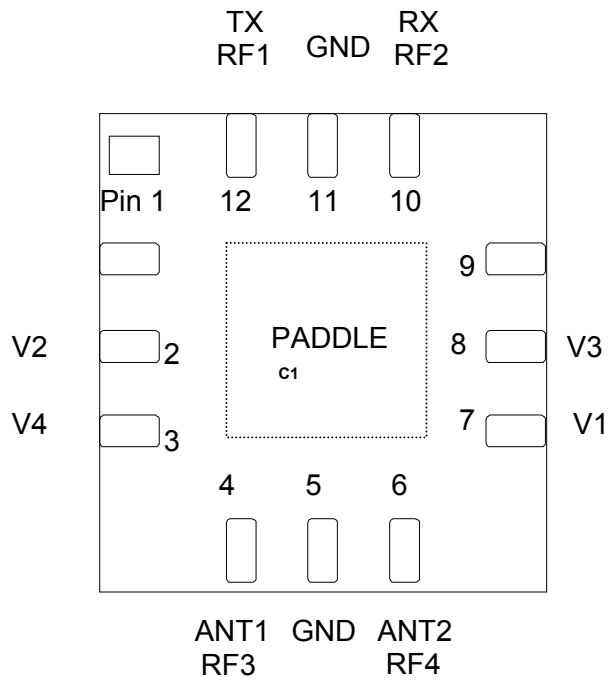
| | |
|---------------------|--|
| Bias Voltages | LOW = 0V to +0.2V HIGH +2.5V to +5.0V |
| Port Impedances | 50Ω |
| Off arm termination | 50Ω |

Typical Measured Performance on Evaluation Board (De-Embedded):

(Measurement Conditions $V_{CTRL}=3V$, $T_{AMBIENT} = 25^{\circ}C$ unless otherwise stated)

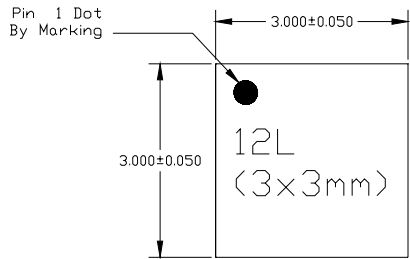


Pad Layout:

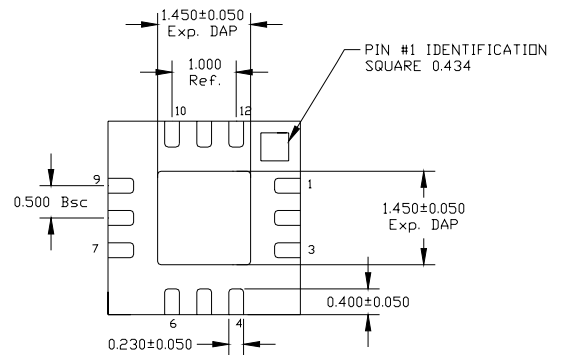


| Pin Number | Description |
|------------|-------------|
| 1 | N/C |
| 2 | V2 |
| 3 | V4 |
| 4 | ANT1 / RF3 |
| 5 | GND |
| 6 | ANT2 / RF4 |
| 7 | V1 |
| 8 | V3 |
| 9 | N/C |
| 10 | RX / RF2 |
| 11 | GND |
| 12 | Tx / RF1 |
| PADDLE | GND |

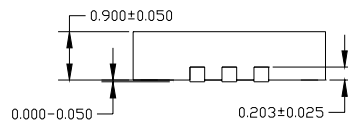
QFN 12 Lead 3*3 Package Outline:



TOP VIEW

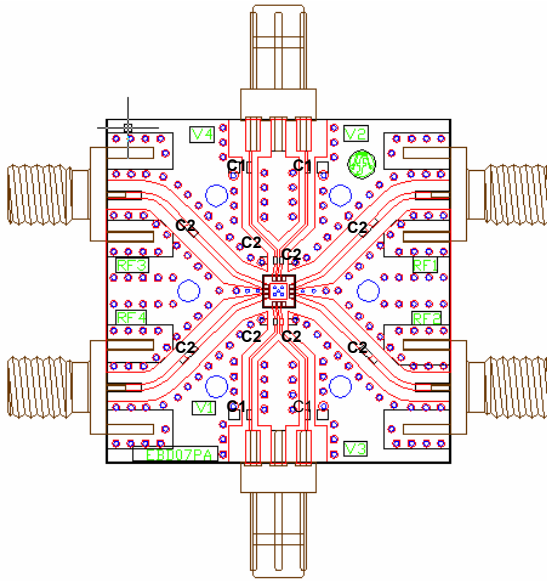


BOTTOM VIEW



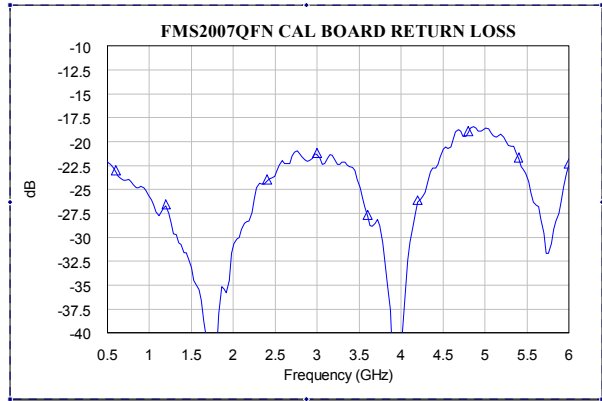
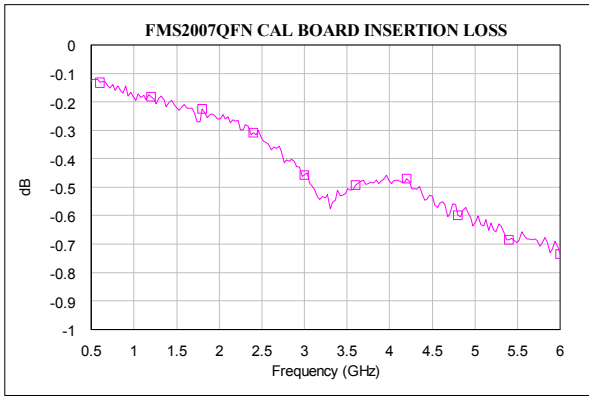
SIDE VIEW

Evaluation Board:



| BOM | |
|-------|--|
| Label | Component |
| C1 | Capacitor, 100pF, 0603 |
| C2 | Capacitor, 47pF, 0402 |
| BOARD | Preferred evaluation board material is 0.25 mm thick ROGERS RT4350. All RF tracks should be 50 ohm characteristic impedance. Absolute placement of surface mount de-coupling capacitors is not critical. |

Evaluation Board De-Embedding Data (Measured):



Ordering Information:

| Part Number | Description |
|--------------------|--|
| FMS2007-001 | Packaged Die |
| FMS2007-001-EB | Packaged die mounted on evaluation board |

Handling Precautions:

To avoid damage to the devices care should be exercised during handling. Proper Electrostatic Discharge (ESD) precautions should be observed at all stages of storage, handling, assembly, and testing. These devices should be treated as Class 1A (0-500V). Further information on ESD control measures can be found in MIL-STD-1686 and MIL-HDBK-263.

Preferred Assembly Instructions:

Please refer to FCSL applications note: FAN 003 (handling and assembly of Filtronic QFN devices)

Disclaimers:

This product is not designed for use in any space based or life sustaining/supporting equipment.